

# (1/3)<0 -1 1 1> Dislocations in Bi<sub>2</sub>Te<sub>3</sub> Nanowires: Defect Crystallography and Relationship to 7-layer Bi<sub>3</sub>Te<sub>4</sub> Defects

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## Introduction

Bi<sub>2</sub>Te<sub>3</sub>, and its iso-structural siblings such as Bi<sub>2</sub>Se<sub>3</sub> and Sb<sub>2</sub>Te<sub>3</sub>, have long been of interest for thermoelectric applications and in recent years have gained prominence in the burgeoning field of topological insulators. It is important to understand the nature of dislocations in these materials since such extended defects are closely connected to the materials growth processes and can affect the thermal and electronic transport properties. The layered structure and possibility for large Burgers vectors in these compounds also raises interesting questions regarding the manner in which dislocations might dissociate. Here, we discuss electron microscopic observations of (1/3)<0-111> dislocations in nanowires of Bi<sub>2</sub>Te<sub>3</sub>. There is significant interest in the growth of Bi<sub>2</sub>Te<sub>3</sub>-based nanowires, motivated by long-standing theoretical predictions of enhanced thermoelectric properties arising in low-dimensional structures of Bi<sub>2</sub>Te<sub>3</sub> [1]. The analysis presented here was made in the course of a broader study exploring how growth and annealing conditions control the resulting crystallinity and internal microstructure in Bi<sub>2</sub>Te<sub>3</sub>-based nanowires [2,3].

### Bi<sub>2</sub>Te<sub>3</sub> Crystal Structure

Hexagonal setting:  $a=0.438$  nm,  $c=3.05$  nm  
Rhombohedral setting:  $a_R=1.048$  nm,  $\alpha_R=24.1^\circ$

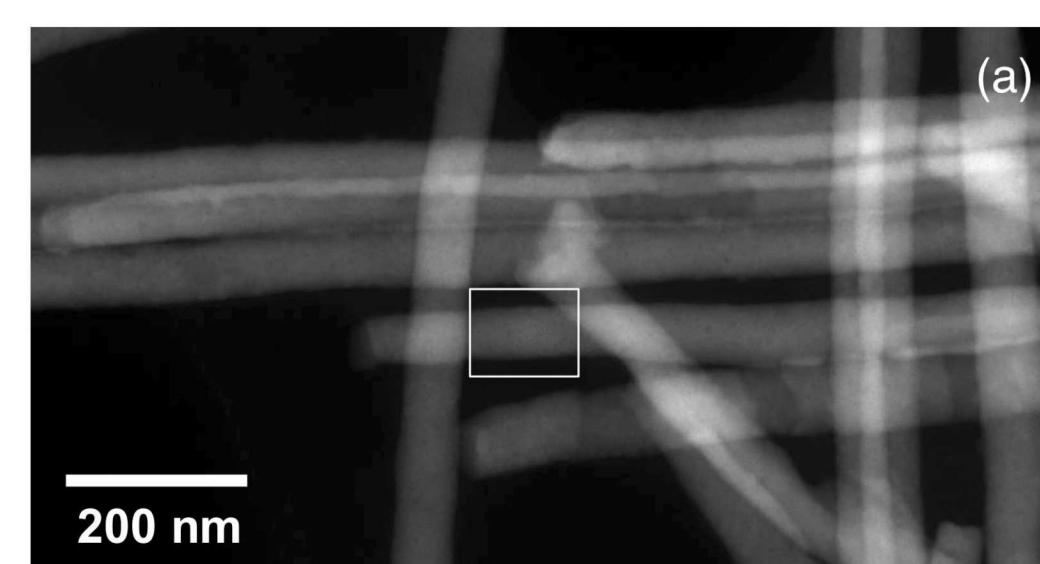
### Dislocation Types

$$\frac{1}{3}\langle 2\bar{1}10 \rangle \quad b=0.438 \text{ nm}$$

$$\frac{1}{3}\langle 0\bar{1}11 \rangle = \langle 001 \rangle_R \quad b=1.048 \text{ nm}$$

- [1] L.D. Hicks, M.S. Dresselhaus, Phys. Rev. B 47 (24) (1993) 16631.  
[2] S. J. Limmer, W. G. Yelton, M. P. Siegal, J. L. Lench-Falk, Jamin Pillars, and D. L. Medlin, Journal of the Electrochemical Society 159 (4) D235-D239 (2012)  
[3] M.P. Siegal, S.J. Limmer, J.L. Lench-Falk, K.J. Erickson, D.L. Medlin, W.G. Yelton, C. Rochford, Journal of Materials Research 29 (2) 182-189 (2014).

## (1/3)<0-111> dislocations form with dissociated cores



Circuit element	x-Component ( $\frac{1}{3}\langle 0110 \rangle$ )	y-Component ( $\frac{1}{3}\langle 0001 \rangle$ )	z-Component ( $\frac{1}{3}\langle 2110 \rangle$ )
(a) Total dislocation (circuit ACDA)			
AC	99	0	$\pm 1$
CD	-30	6	0
DF	-96	0	0
FA	25	-5	$\pm 1$
Sum:	-2	1	0

$$b = \frac{1}{3}\langle 011 \rangle_R = \langle 001 \rangle_R$$

$$|b| = 1.048 \text{ nm}$$

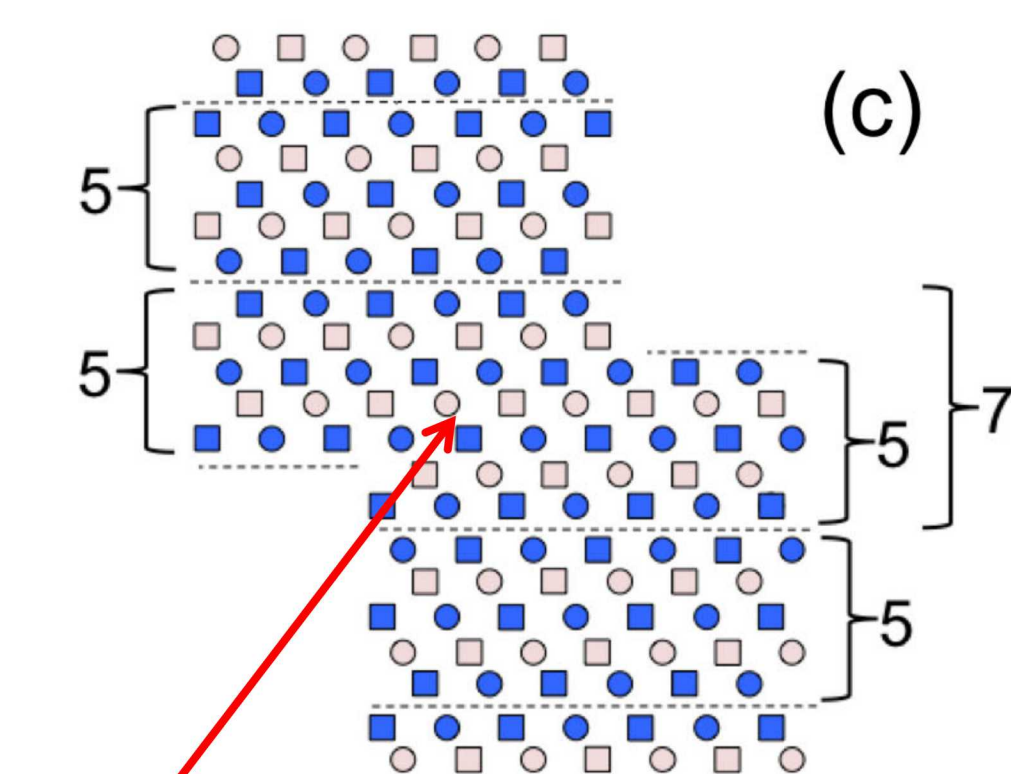
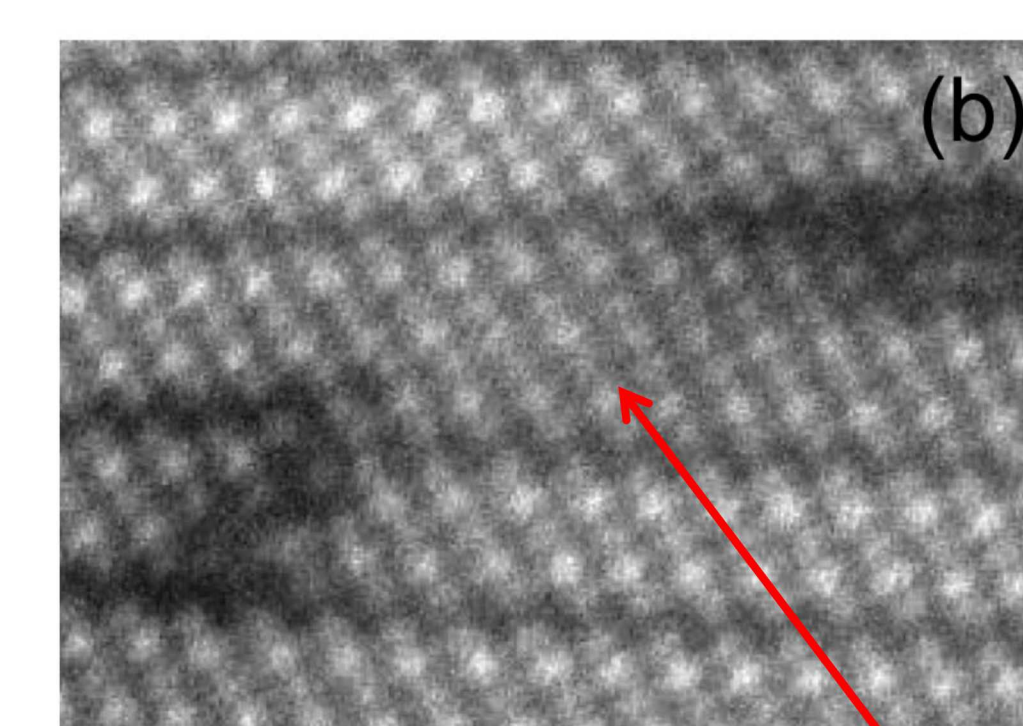
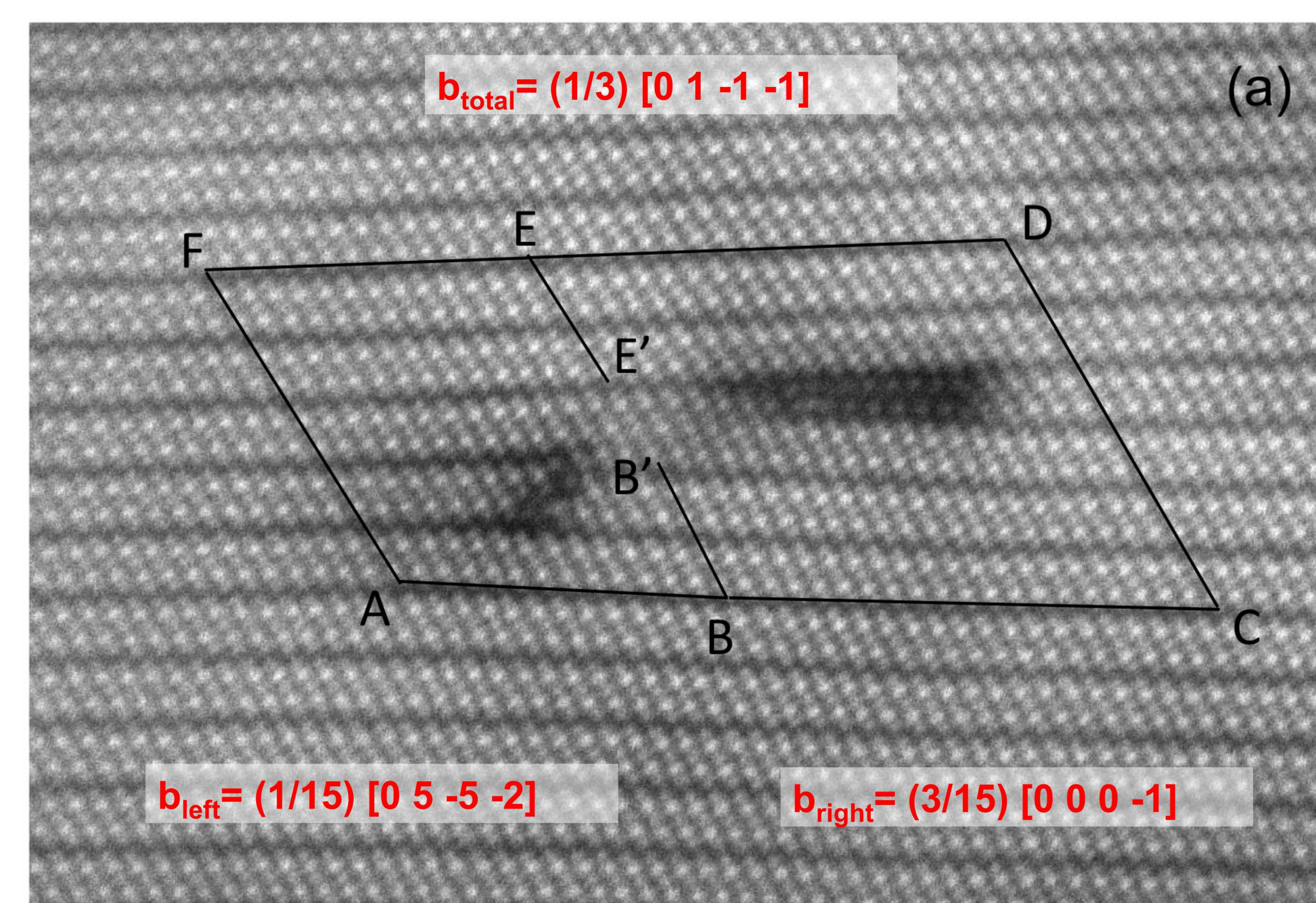
Circuit element	x-Component ( $\frac{1}{3}\langle 0110 \rangle$ )	y-Component ( $\frac{1}{3}\langle 0001 \rangle$ )	z-Component ( $\frac{1}{3}\langle 2110 \rangle$ )
(b) Left partial dislocation (circuit ABEFA)			
AB	39	0	$\pm 1$
BB'	-10	2	0
B'E'	-7	$\approx 7/5$	$\pm 1$
E'E	-10	2	0
EF	-39	0	$\pm 1$
FA	25	-5	$\pm 1$
Sum:	-2	$\approx 2/5$	0

$$b \approx \frac{1}{3}\langle 0552 \rangle_R = \frac{1}{3}\langle 114 \rangle_R$$

$$|b| = 0.479 \text{ nm}$$

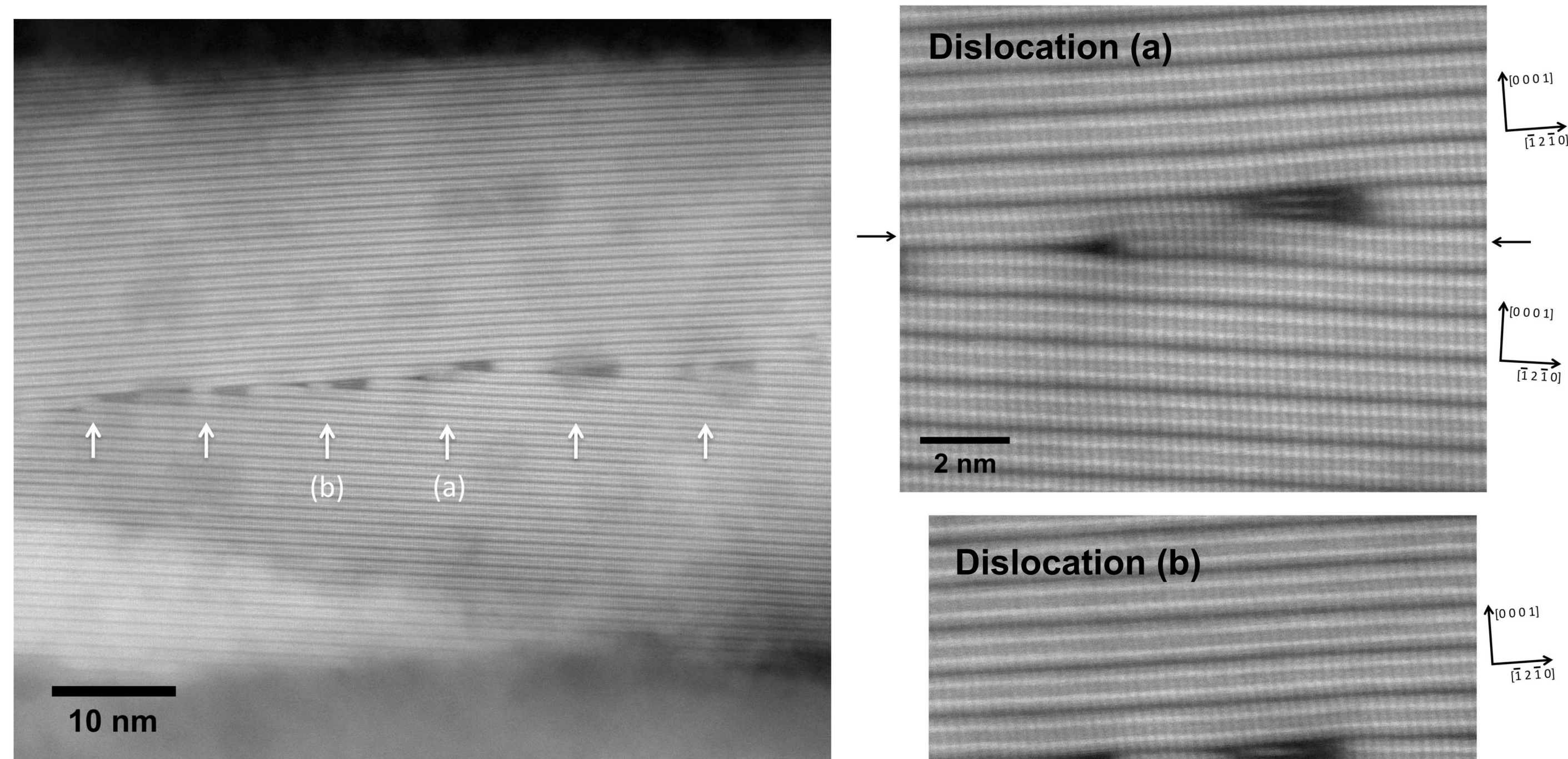
Circuit element	x-Component ( $\frac{1}{3}\langle 0110 \rangle$ )	y-Component ( $\frac{1}{3}\langle 0001 \rangle$ )	z-Component ( $\frac{1}{3}\langle 2110 \rangle$ )
(c) Right partial dislocation (circuit BCDEB)			
BC	60	0	0
CD	-30	6	0
DE	-57	0	$\pm 1$
EE'	10	-2	0
E'B'	7	$\approx -7/5$	$\pm 1$
B'B	10	-2	0
Sum:	0	$\approx 3/5$	0

$b \approx \frac{2}{3}\langle 0001 \rangle_R = \frac{1}{3}\langle 111 \rangle_R$   
 $|b| = 0.610 \text{ nm}$   
For the FSRH sign convention, with the dislocation line direction defined as positive out of the board, the Burgers vector,  $b$ , is the negative of the vector sum of the individual circuit elements referenced to the perfect crystal



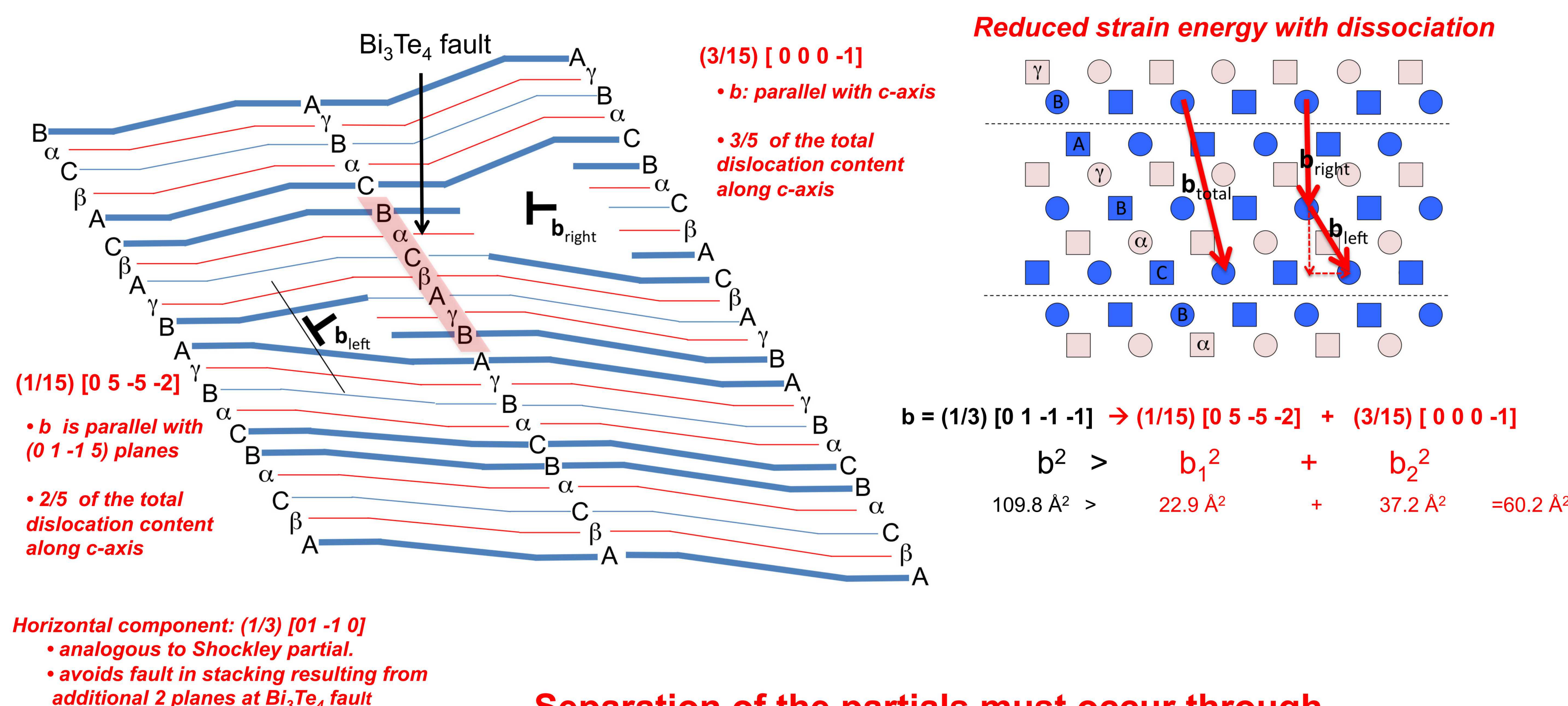
Core Structure:  
Bi<sub>3</sub>Te<sub>4</sub> 7-layer fault

## Array of (1/3)<0-111> dislocations at a low angle grain boundary



HAADF-STEM image of a Bi<sub>2</sub>Te<sub>3</sub> nanowire imaged along a <10-10> orientation. A low angle grain boundary, which is vicinal to the {0001} planes, runs horizontally across the middle section of the wire. The 5.5° tilt misorientation between the two grains is accommodated by an array of dissociated (1/3)<0-111> dislocations, indicated by the arrows.

## Dissociation Mechanism



Separation of the partials must occur through non-conservative climb-dissociation process.

Resulting 7-layer, Bi<sub>3</sub>Te<sub>4</sub> fault provides mechanism to accommodate Te loss during annealing.

## Experimental Methods

Bi<sub>2</sub>Te<sub>3</sub> nanowires were prepared by electroplating into nanoporous anodic aluminum oxide (AAO) templates using procedures similar to those reported in [1]. AAO templates were formed by anodizing Al(Nd)/W film stacks deposited on silicon wafers. Anodization was conducted at 40 V and 1 °C in 3 wt% oxalic acid. After fully anodizing the Al(Nd) layer, the interfacial WO<sub>3</sub> layer was removed in a 0.2 M pH 7 phosphate buffer, and the pores were widened to ~75 nm in 5 wt.% H<sub>3</sub>PO<sub>4</sub> at 30 °C. The nanowires were grown in the AAO nanopores by pulsed-current electrochemical deposition using the bath described by Banga *et al.* (6 mM Bi(NO<sub>3</sub>)<sub>3</sub>, 7 mM Na<sub>2</sub>TeO<sub>3</sub>, 0.3 M L-tartaric acid and 2 M HNO<sub>3</sub>) [2]. We employed an on-current of -20 mA/cm<sup>2</sup> applied for 0.1 s, followed by an off-period (no current) of 0.9 s, repeating this cycle for 50 minutes. The solutions were sparged with N<sub>2</sub> for a minimum of 20 minutes prior to deposition and blanketed with N<sub>2</sub> during deposition.

To form freestanding arrays of nanowires, the AAO template was removed by etching in de-aerated 5 wt% H<sub>3</sub>PO<sub>4</sub> solution at 30 °C for 6 hours with N<sub>2</sub> bubbling. After etching, the samples were rinsed repeatedly with deionized water, and then isopropanol. Finally, the samples were dried with supercritical CO<sub>2</sub> (Samdri-PVT-3D critical point dryer, Tousimis). The freestanding nanowire arrays were annealed at 300 °C for 30 min in an atmosphere of Ar-3% H<sub>2</sub> flowing at ~100 sccm. The specimens for electron microscopic observation were prepared by dispersing the nanowires onto holey carbon support grids by ultrasonication in isopropyl alcohol. Observations were conducted using an aberration-corrected FEI Titan TEM operated at 300 keV in scanning mode using a high angle annular dark field (HAADF) detector.

[1] Limmer S.J., Yelton W.G., Siegal M.P., Lench-Falk J.L., Pillars J., Medlin D.L. (2012) Electrochemical deposition of Bi<sub>2</sub>(Te,Se)<sub>3</sub> nanowire arrays on Si. Journal of the Electrochemical Society 159 (4):D235-D239.

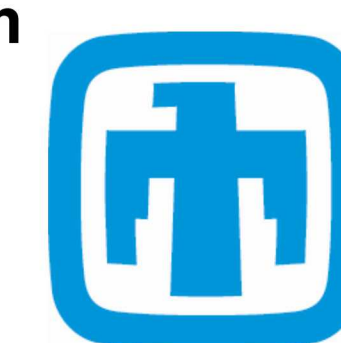
[2] Banga D., Lench-Falk J.L., Medlin D.L., Stavila V., Yang N.Y., Robinson D.B., Sharma P.A. (2012) Periodic Modulation of Sb Stoichiometry in Bi<sub>2</sub>Te<sub>3</sub>/Bi<sub>2</sub>Sb<sub>2</sub>Te<sub>3</sub> Multilayers using Pulsed Electrodeposition. Crystal Growth & Design 12 (3):1347-1353

## Conclusions

We have discovered 1/3<0-111>-type dislocations in Bi<sub>2</sub>Te<sub>3</sub> nanowires. Because these dislocations possess a large Burgers vector component along the c-axis, they are well suited to accommodate intergranular misorientations at grain boundaries with inclinations vicinal to {0001}. Here, we observed such a dislocation array at a grain boundary in an electrodeposited and annealed nanowire. We would also expect such dislocations to arise at low-angle grain boundaries in Bi<sub>2</sub>Te<sub>3</sub> grown or consolidated by other methods, particularly those that lead to lamellar grain morphologies and <0001> textures, as occur in film growth and pressed powders. The observed dislocations form in a dissociated configuration consisting of two partial dislocations that separate a local 7-layer defect region, consistent with a single septuple unit of Bi<sub>3</sub>Te<sub>4</sub>. Analysis of the geometric properties of the partial dislocations helps to explain the local stacking arrangements and possibilities for core-rearrangements. The dissociation likely occurs to reduce the strain energy of the full 1/3<0-111> dislocation, which has a remarkably large Burgers vector ( $b=1.048$  nm) encompassing the width of a full Bi<sub>2</sub>Te<sub>3</sub> quintuple unit. These observations suggest a mechanism for accommodating tellurium deficiency by the heterogeneous nucleation of septuple units at the cores of pre-existing 1/3<0-111> dislocations.

D.L. Medlin, K.J. Erickson, S.J. Limmer, W.G. Yelton, M.P. Siegal, Journal of Materials Science 49 (11) (2014) 3970-3979

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